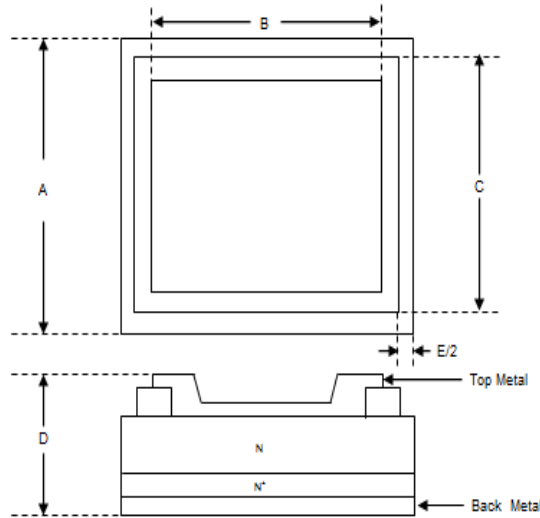


BM0150BG

150V, 30A⁽¹⁾, XTBR series Schottky

Mechanical Data

Chip Drawing	Item	Information	
	Die Size (A)	3809 μm	150 mil
	Top Metal Pad Size (B)	3622.5 μm	142.6 mil
	Passivation Seal (C)	3729 μm	146.8 mil
	Wafer Thickness (D)	254±15 μm	10±0.6 mil
	Scribe Line Width (E)	80 μm	3.15 mil
	Wafer Diameter	6 inch	
	Gross Die	1059	
	Top Side Metallization/ Layer Thickness	Ag / 3 ±0.3 μm	
	Back Side Metallization/ Layer Thickness	Ag / 2 ±0.2 μm	
	Recommended Storage Environment	Store in original container, in dry nitrogen, (6 months at an ambient temperature of 23°C±3°C)	

Electrical Characteristics in C/P test (T_J =25°C)

Parameter	Description	Min.	Typ.	Max.	Unit	Test Condition
V _{BR}	Reverse Breakdown Voltage	150	—	—	V	I _R =300μA
V _F	Instantaneous Forward Voltage	—	0.485	0.50	V	I _F =3A ⁽²⁾
		—	0.675	0.69	V	I _F =10A ⁽²⁾
I _R	Reverse Leakage Current	—	30	50	μA	V _R =150V
T _J , T _{STG}	Operating and Storage Temperature	-40°C to 150°C Max				